



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

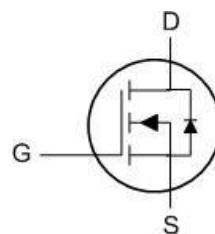
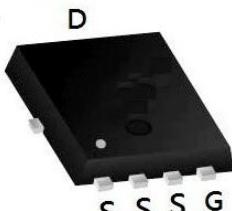
Product Summary

BVDSS	RDS(ON)	ID
30V	3.0mΩ	120 A

Description

The XXW120N03F is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications. The XXW120N03F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

PDFN5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V _{DS}	Drain-Source Voltage	30		V
V _{GS}	Gate-Source Voltage	±20		V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	120		A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	75		A
I _{DM}	Pulsed Drain Current ²	384		A
EAS	Single Pulse Avalanche Energy ³	198		mJ
I _{AS}	Avalanche Current	53.8		A
P _D @T _C =25°C	Total Power Dissipation ⁴	62.5		W
P _D @T _A =25°C	Total Power Dissipation ⁴	6	2.42	W
T _{STG}	Storage Temperature Range	-55 to 175		°C
T _J	Operating Junction Temperature Range	-55 to 175		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	25	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.4	°C/W

N-Ch 30V Fast Switching MOSFETs
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

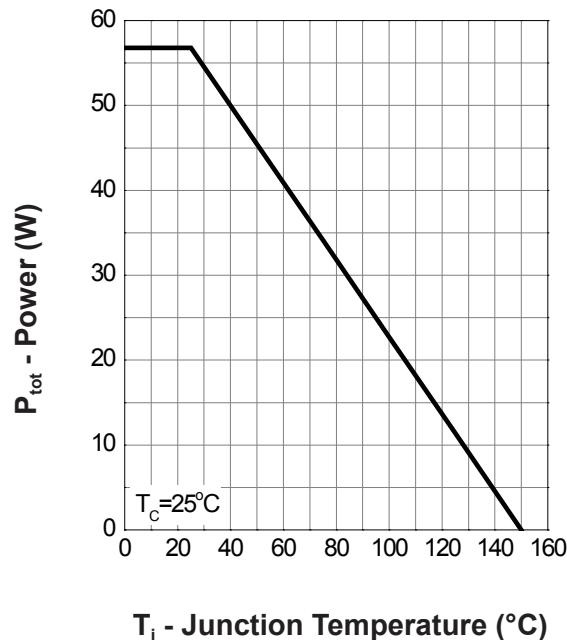
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=24\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
		$\text{T}_J=85^\circ\text{C}$	-	-	30	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	1.4	1.7	2.5	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	±100	nA
$\text{R}_{\text{DS(ON)}}^{\text{d}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	3	3.8	$\text{m}\Omega$
		$\text{T}_J=125^\circ\text{C}$	-	4.4	-	
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=15\text{A}$	-	4.0	5.5	
Gfs	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_{\text{DS}}=10\text{A}$	-	24.6	-	S
Diode Characteristics						
$\text{V}_{\text{SD}}^{\text{d}}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=20\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	0.8	1.1	V
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{DS}}=20\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$	-	35.6	-	ns
t_{a}	Charge Time		-	19.3	-	
t_{b}	Discharge Time		-	16.3	-	
Q_{rr}	Reverse Recovery Charge		-	26	-	nC
Dynamic Characteristics ^e						
R_{G}	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$	-	1	2	Ω
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=15\text{V}, \text{Frequency}=1.0\text{MHz}$	-	2485	2971	pF
C_{oss}	Output Capacitance		-	850	-	
C_{rss}	Reverse Transfer Capacitance		-	85	-	
$\text{t}_{\text{d(ON)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=15\text{V}, \text{R}_{\text{L}}=15\Omega, \text{I}_{\text{DS}}=1\text{A}, \text{V}_{\text{GEN}}=10\text{V}, \text{R}_{\text{G}}=6\Omega$	-	12.4	23	ns
t_{r}	Turn-on Rise Time		-	9.5	18	
$\text{t}_{\text{d(OFF)}}$	Turn-off Delay Time		-	27.2	49	
t_{f}	Turn-off Fall Time		-	35.2	64	
Gate Charge Characteristics ^e						
Q_{g}	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	20.6	28.8	nC
Q_{g}	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	9.8	-	
Q_{gth}	Threshold Gate Charge		-	1.8	-	
Q_{gs}	Gate-Source Charge		-	3.8	-	
Q_{gd}	Gate-Drain Charge		-	3.7	-	

Note d : Pulse test ; pulse width $\leq300\mu\text{s}$, duty cycle $\leq2\%$.

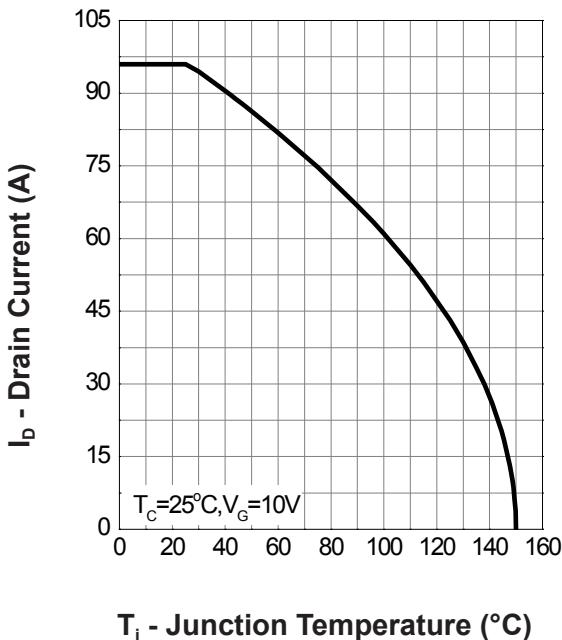
Note e : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

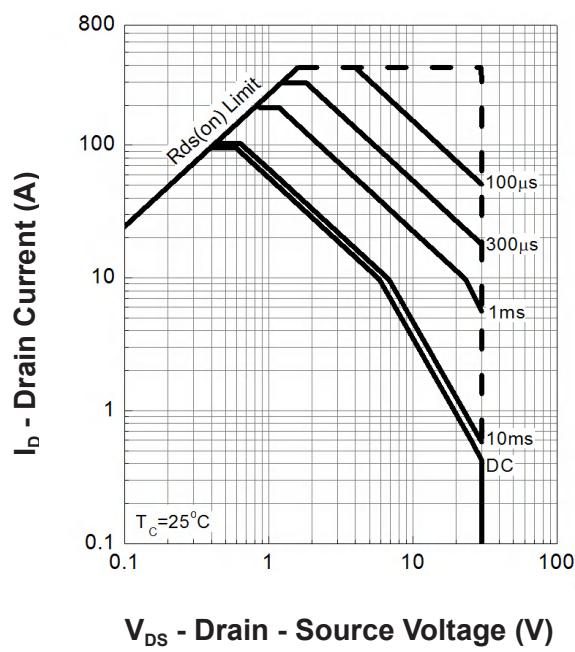
Power Dissipation



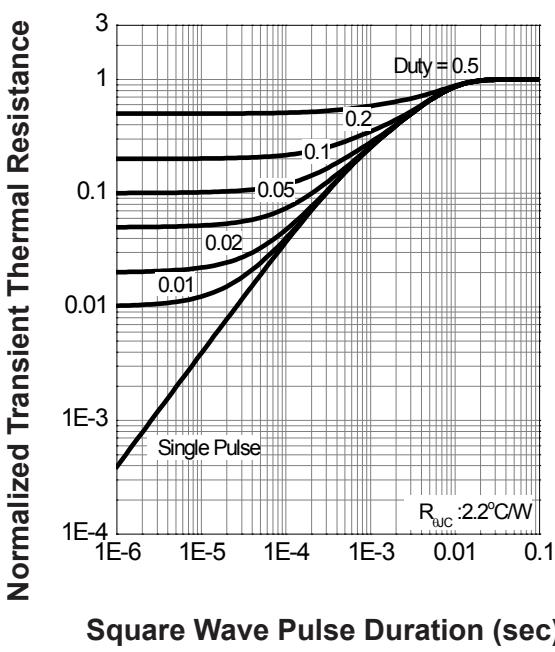
Drain Current

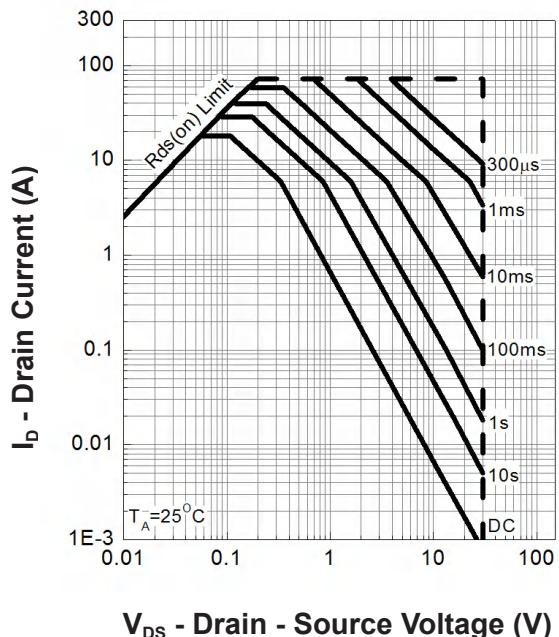
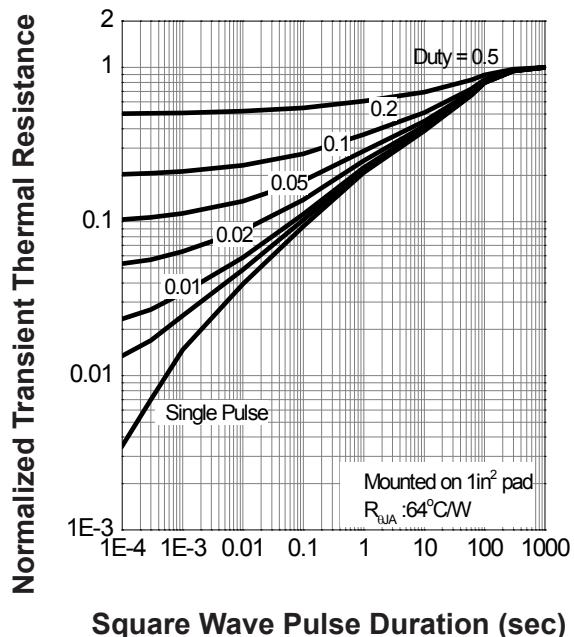
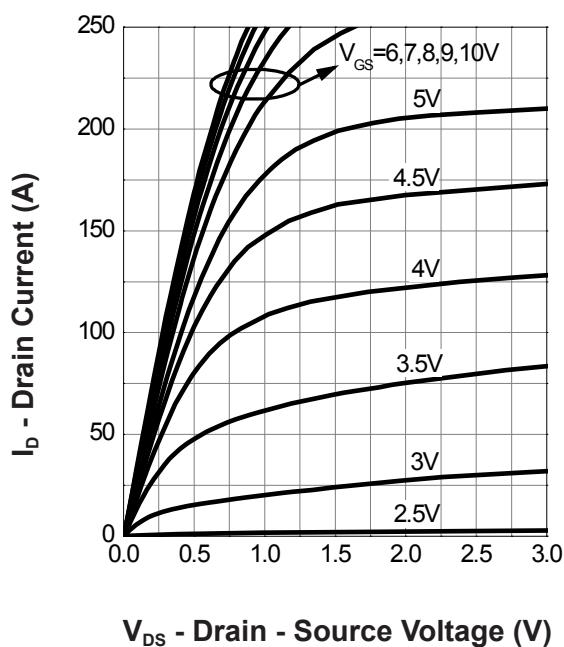
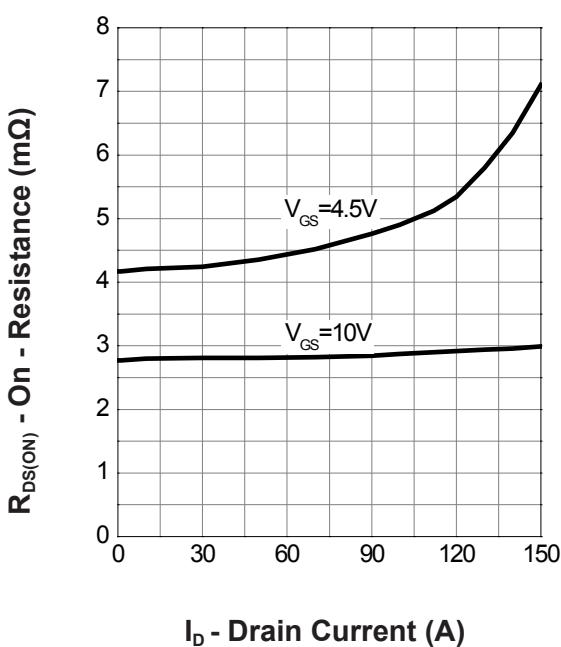


Safe Operation Area



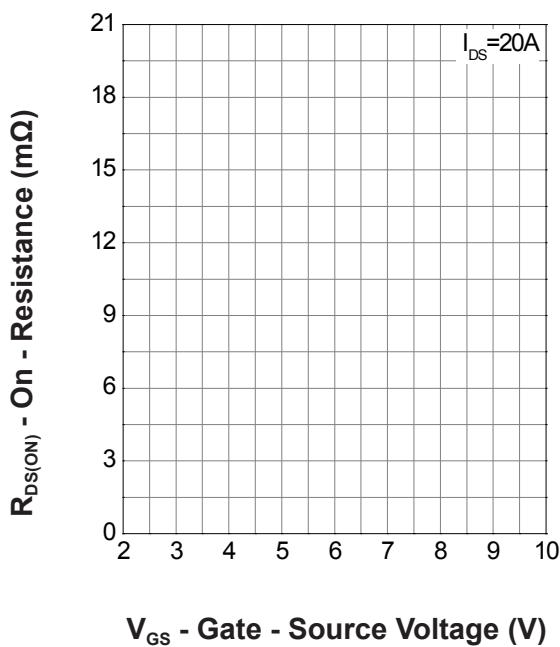
Thermal Transient Impedance



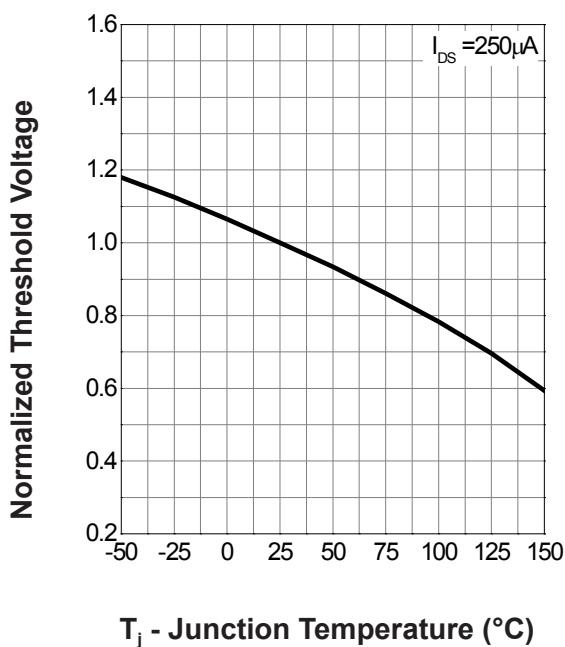
Typical Operating Characteristics(Cont.)
Safe Operation Area

Thermal Transient Impedance

Output Characteristics

Drain-Source On Resistance


Typical Operating Characteristics(Cont.)

Gate-Source On Resistance



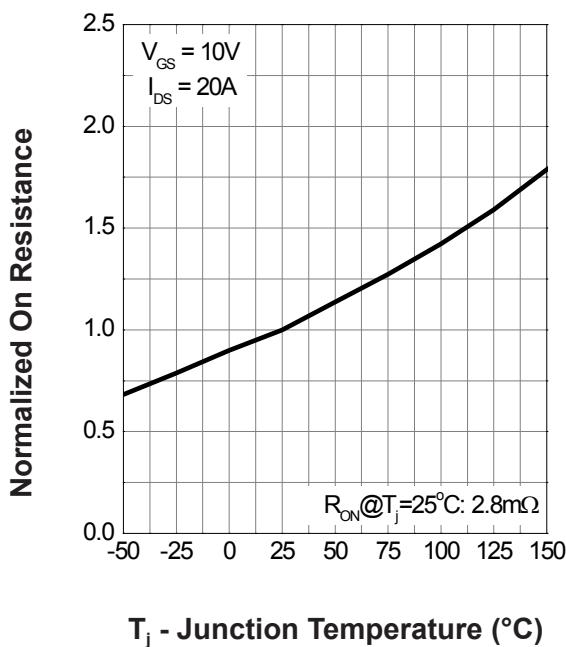
Gate Threshold Voltage



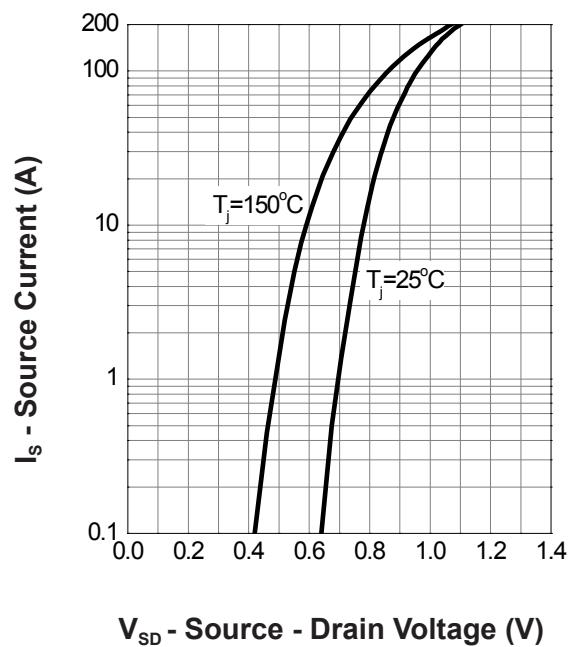
V_{GS} - Gate - Source Voltage (V)

T_j - Junction Temperature (°C)

Drain-Source On Resistance

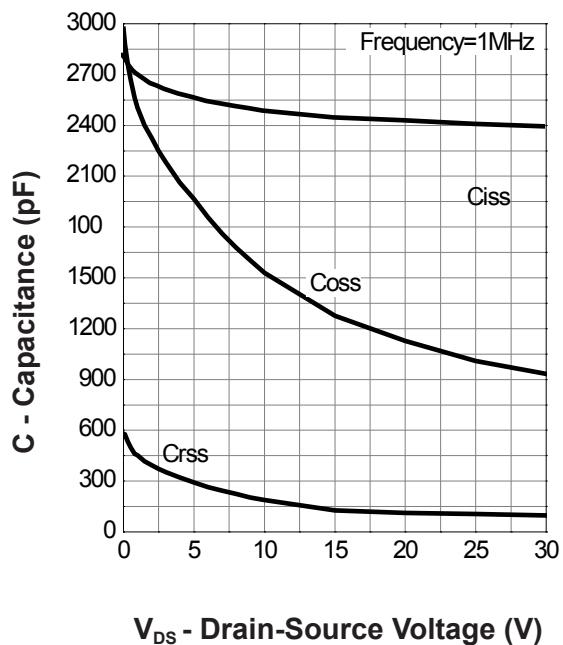
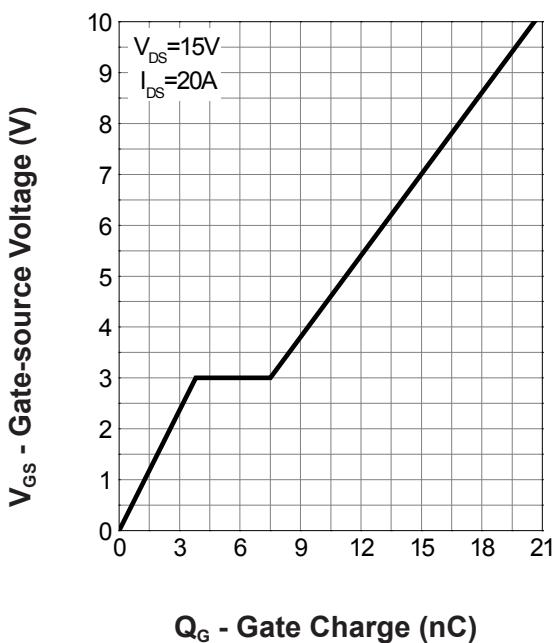


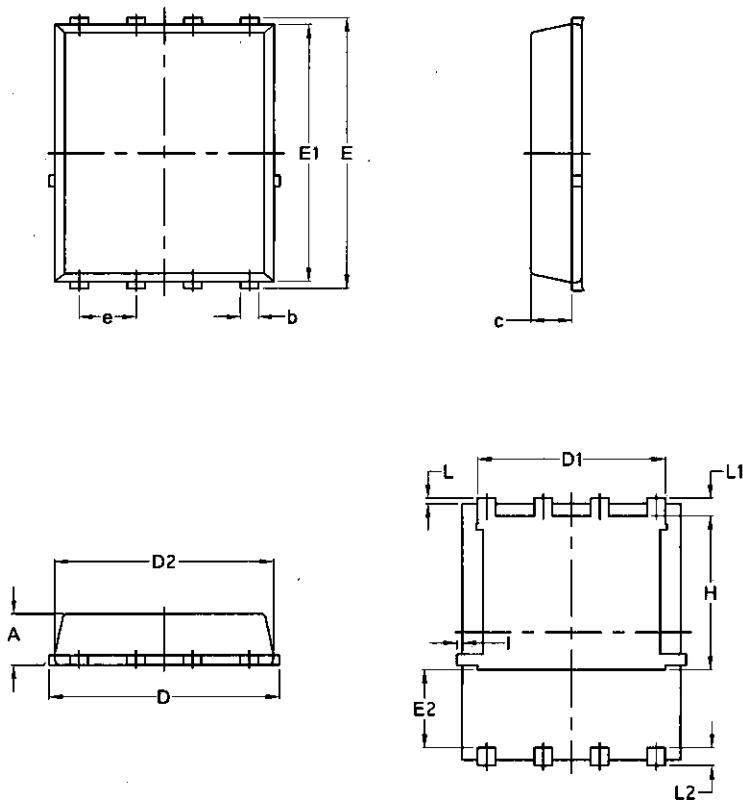
Source-Drain Diode Forward



T_j - Junction Temperature (°C)

V_{SD} - Source - Drain Voltage (V)

Typical Operating Characteristics(Cont.)
N-Ch 30V Fast Switching MOSFETs
Capacitance

Gate Charge


Package Mechanical Data-DFN5*6-8L-Single


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070